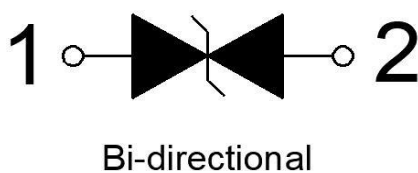


Features

- 2-pin lead-less package
- Junction capacitance (Typ value: 0.09pF)
- Peak Pulse Current (8/20μs):5A
- IEC61000-4-2 (ESD) ±20kV (air), ±15kV (contact)
- Low clamping voltage
- Low leakage current
- Working voltages:3.3V
- RoHS Compliant

Appearance & Symbol



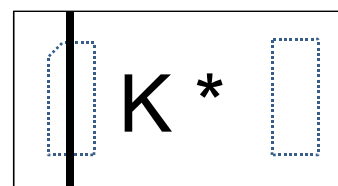
Mechanical Characteristics

- Package: DFN0603-2L
- Lead Finish:Matte Tin
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Tape Reel :15000pcs

Applications

- Antenna
- High-speed signal transmission port
- Notebooks and Handhelds, Audio Players, Peripherals
- Personal Digital Assistants, Portable Instrumentation
- Keypads, Side Keys, LCD Displays

Marking Information



K =Marking Code
* =Date Code

Absolute Maximum Ratings (T=25°C, RH=45%-75%, unless otherwise noted)

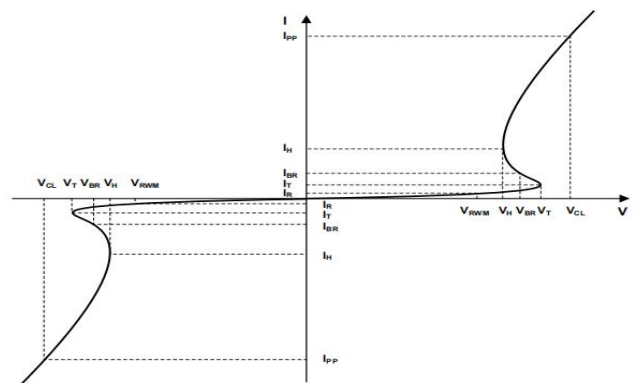
Parameters	Symbol	Value	Unit
Peak Pulse Current (8/20μs)	I_{PP}	5	A
ESD follow IEC 61000-4-2 (Air)	V_{ESD}	±20	KV
ESD follow IEC 61000-4-2 (Contact)		±15	
Operating Temperature Range	T_J	-55 to +125	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				±3.3	V
Reverse Breakdown Voltage	V_{BR}	$I_R = 1mA$	5.5		9	V
Reverse Leakage Current	I_R	$V_R = 3.3V$			0.1	uA
Holding Voltage	V_H	$I_H = 100mA$	5.2			V
Clamping voltage	V_C	$I_{PP} = 1A, T_P = 8/20\mu s$		6.5	8	V
Clamping voltage	V_C	$I_{PP} = 5A, T_P = 8/20\mu s$		8	12	V
Junction capacitance	C_J	$V_R = 0V, f = 1MHz$		0.09	0.125	pF

Electronics Parameter

Symbol	Parameter
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
P_{PP}	Peak Pulse Power



Typical Characteristics

FIG1: Power rating derating curve

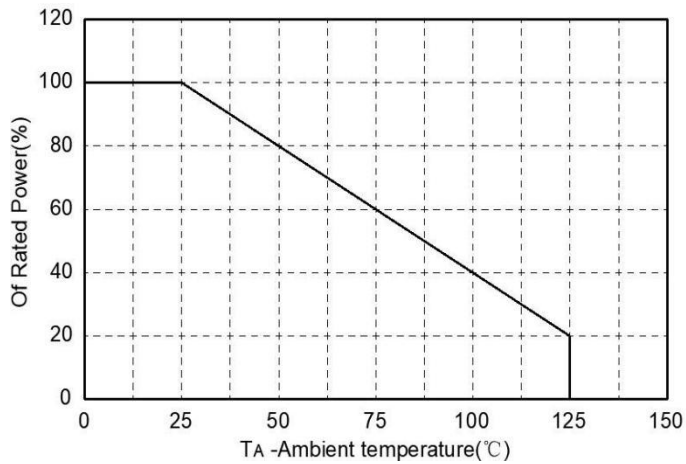
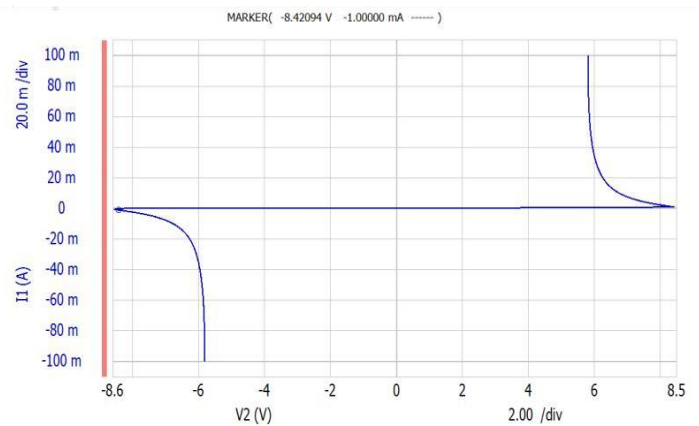
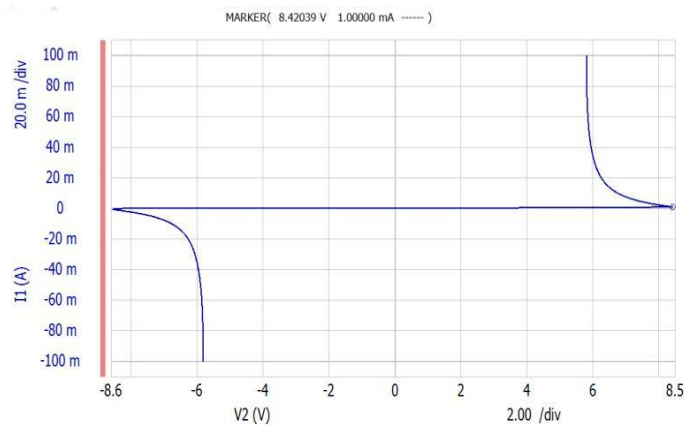
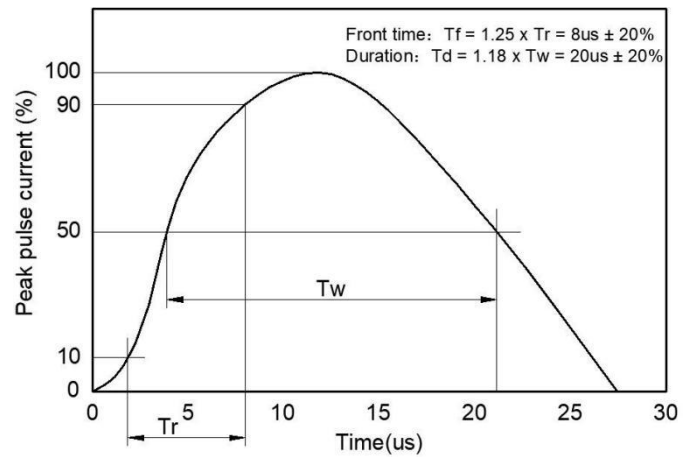
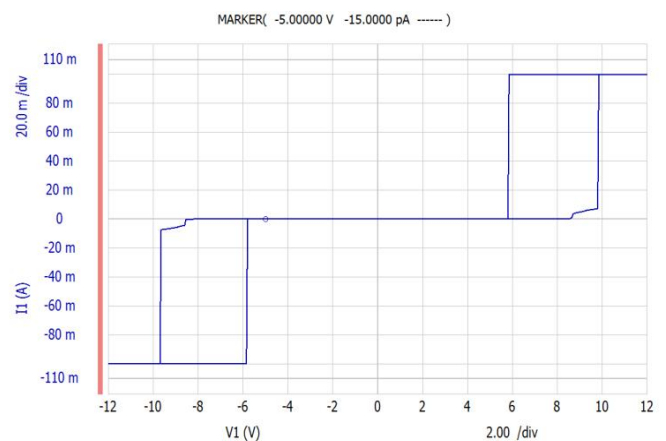
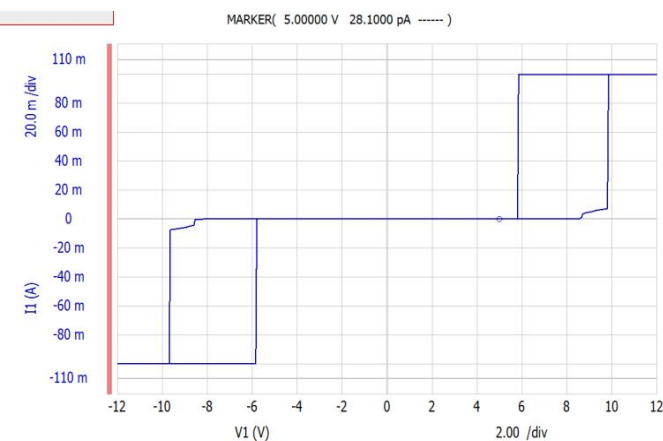


FIG2: pulse Waveform



I-V Curve current sweep from -100mA to 100mA

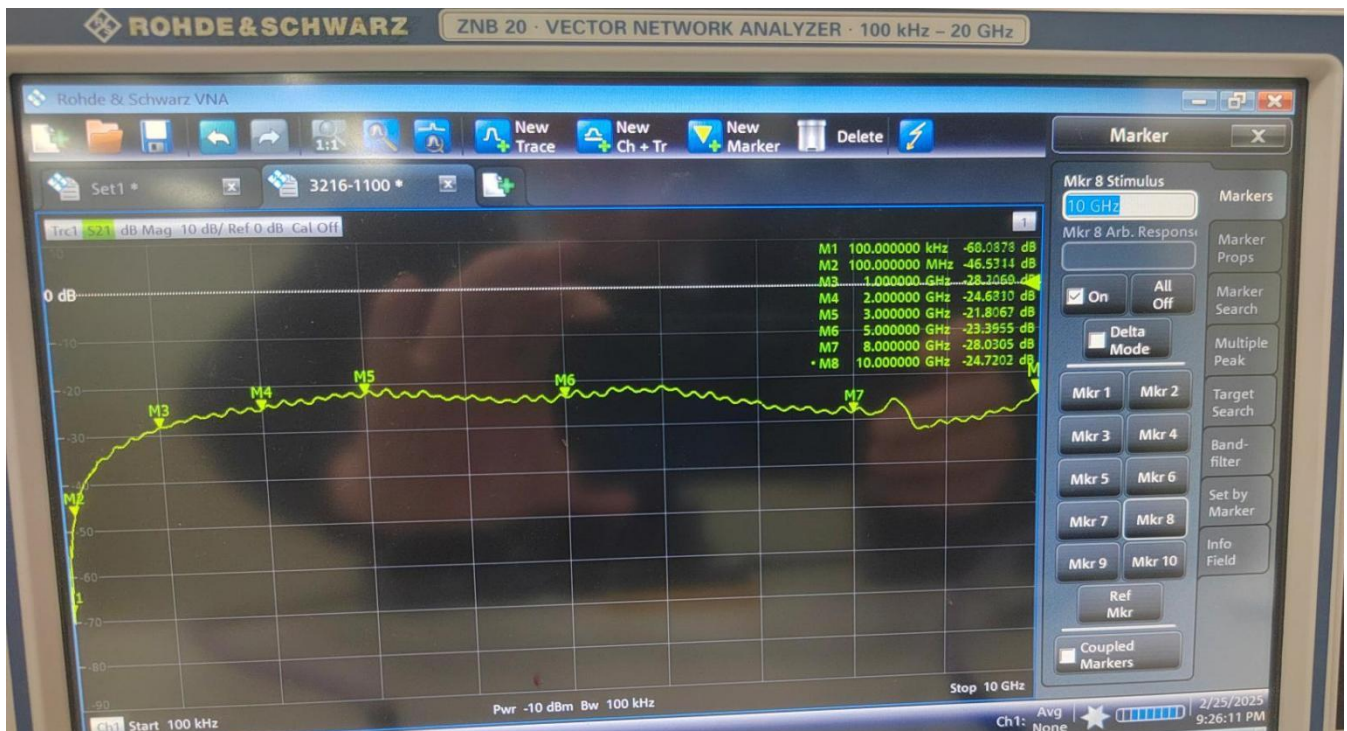


I-V Curve voltage sweep from -12V to 12V

Typical Characteristics



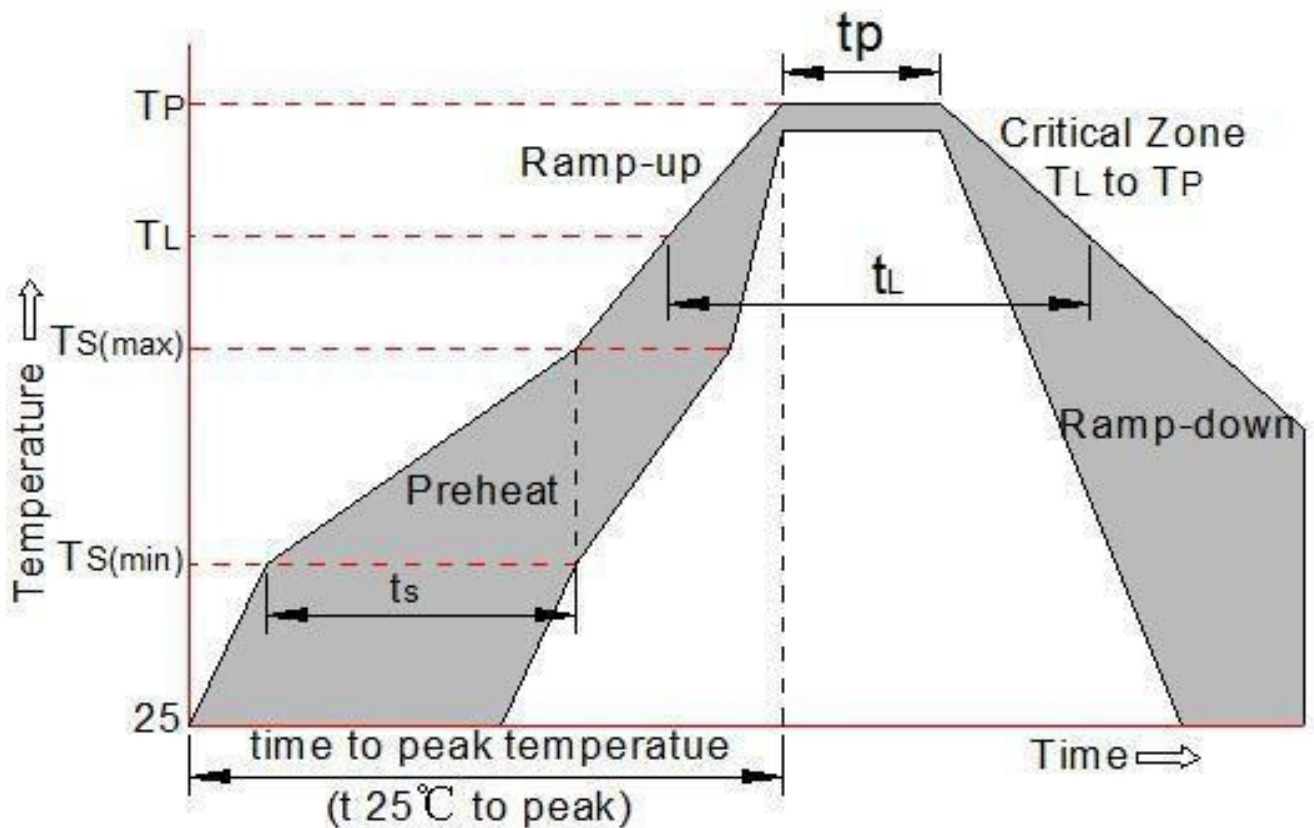
Test at 1.0 to 3.0 GHz



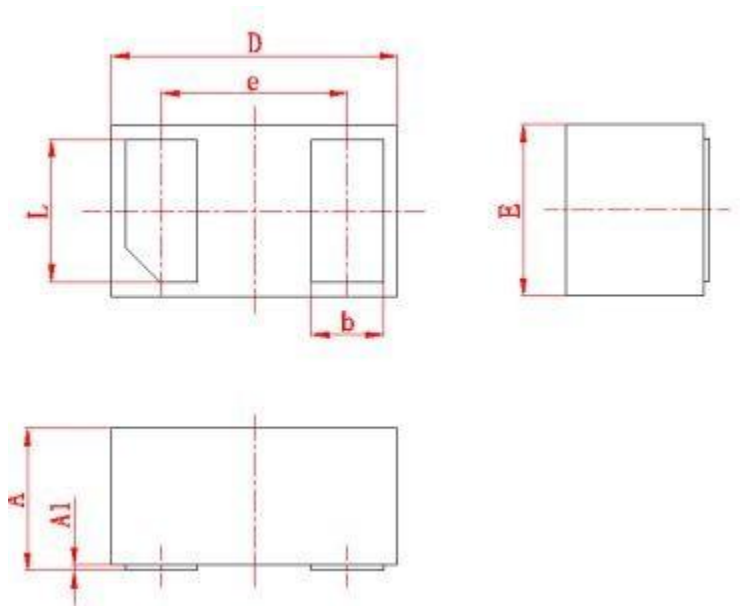
Insertion loss test at 100KHz to 10.0 GHz

Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

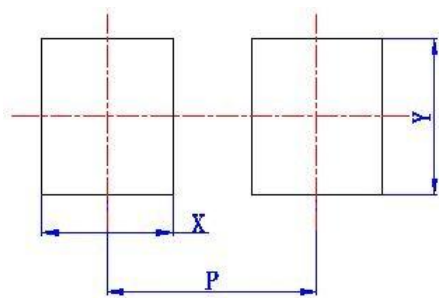


Package mechanical data



Symbol	Dimension in Millimeters	
	min	max
A	0.27	0.37
A1	0	0.05
D	0.55	0.65
E	0.25	0.36
e	(0.4)	
b	0.09	0.2
L	0.17	0.25

Suggested Land Pattern



Symbol	Dimension in Millimeters
	typ
X	(0.32)
Y	(0.40)
P	(0.47)